


HEAT SINK-LEAD FRAME STRUCTURE

Patent number: WO9820718
Publication date: 1998-05-14
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Classification:
- **International:** H05K7/20
- **European:** H01L23/433E; H01L23/495H
Application number: WO1997US19309 19971103
Priority number(s): US19960746064 19961106

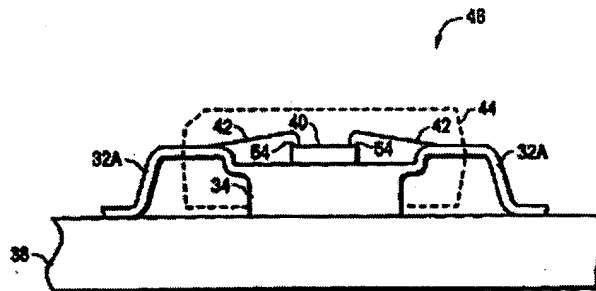
Cited documents:

 US5289344

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Abstract of WO9820718

A surface mount package includes a unitary combination heat sink and lead frame, the heat sink (34) having mounted thereon a semiconductor die (40) and being mounted to a printed circuit board (38). The heat sink (34) and certain leads (32a) of the lead frame provide heat conduction paths from the die (40) to the printed circuit board (38), for highly efficient dissipation of heat.



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